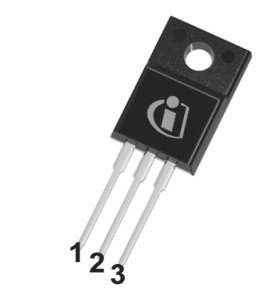
MOSFET

StrongIRFET™ 2 Power-Transistor

PG-TO220 FP



Features

- Optimized for a wide range of applications
- N-Channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Qualified according to JEDEC Standard

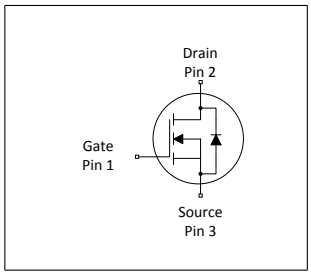


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	8.2	mΩ
I_D	46	A
Q_{oss}	38	nC
Q_G	28	nC

Type / Ordering Code	Package	Marking	Related Links
IPA082N10NF2S	PG-TO220 FullPAK	082N10NS	-

Table of Contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- -	- -	46 32	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C
Pulsed drain current[2]	$I_{D,pulse}$	-	-	184	A	T_A=25 °C
Avalanche energy, single pulse[3]	E_{AS}	-	-	80	mJ	I_D=40 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	35	W	T_C=25 °C
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	4.3	°C/W	-

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.2	3.0	3.8	V	V_{DS}=V_{GS}, I_D=46 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1.0 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance[4]	$R_{DS(on)}$	- -	7.3 8.9	8.2 10.3	mΩ	V_{GS}=10 V, I_D=30 A V_{GS}=6 V, I_D=15 A
Gate resistance	R_G	-	1.1	-	Ω	-
Transconductance[5]	g_{fs}	31	-	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=30 A

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] See Diagram 3 for more detailed information
[3] See Diagram 13 for more detailed information
[4] $R_{DS(on)}$ is specified at a distance of 1.8 mm distance to the package body; mounting at a larger distance increases the overall package resistance of approximately 0.04 mOhm/mm per leg.
[5] Defined by design. Not subject to production test.

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	2000	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance	C_{oss}	-	320	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Reverse transfer capacitance	C_{rss}	-	15	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	11	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	20	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	16	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	5	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω

Table 6 Gate charge characteristics[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	9.3	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	6.0	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate to drain charge	Q_{gd}	-	6.0	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	9.3	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate charge total[2)]	Q_g	-	28	42	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	4.7	-	V	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Output charge	Q_{oss}	-	38	-	nC	V_{DS}=50 V, V_{GS}=0 V

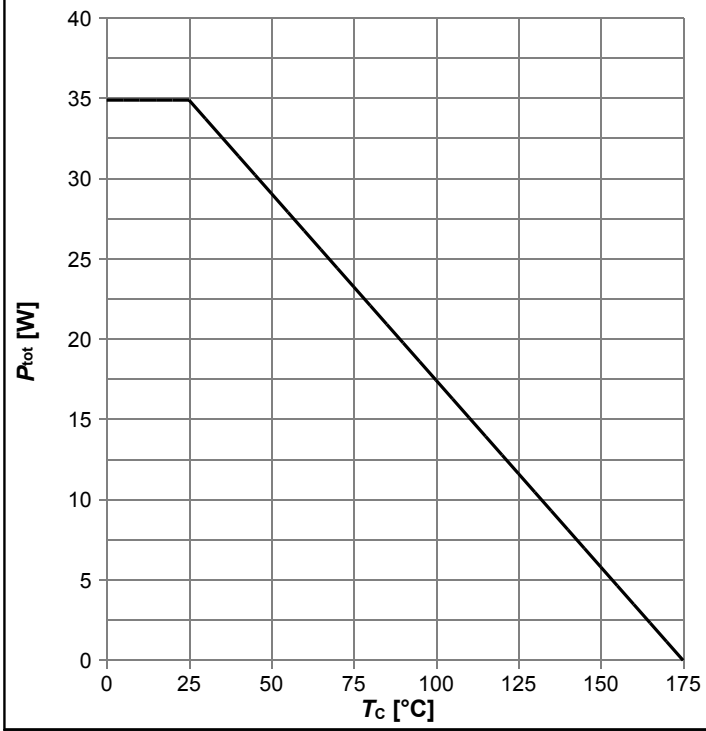
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	26	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	184	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.83	1.2	V	V_{GS}=0 V, I_F=15 A, T_j=25 °C
Reverse recovery time	t_{rr}	-	33	-	ns	V_R=50 V, I_F=15 A, di_F/dt=500 A/µs
Reverse recovery charge	Q_{rr}	-	199	-	nC	V_R=50 V, I_F=15 A, di_F/dt=500 A/µs

[1)] See ″Gate charge waveforms″ for parameter definition
[2)] Defined by design. Not subject to production test.

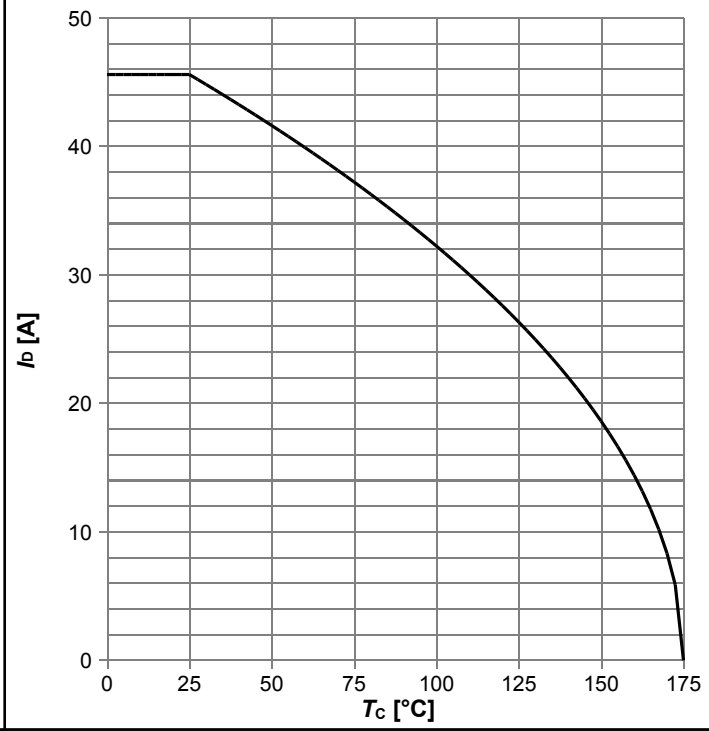
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



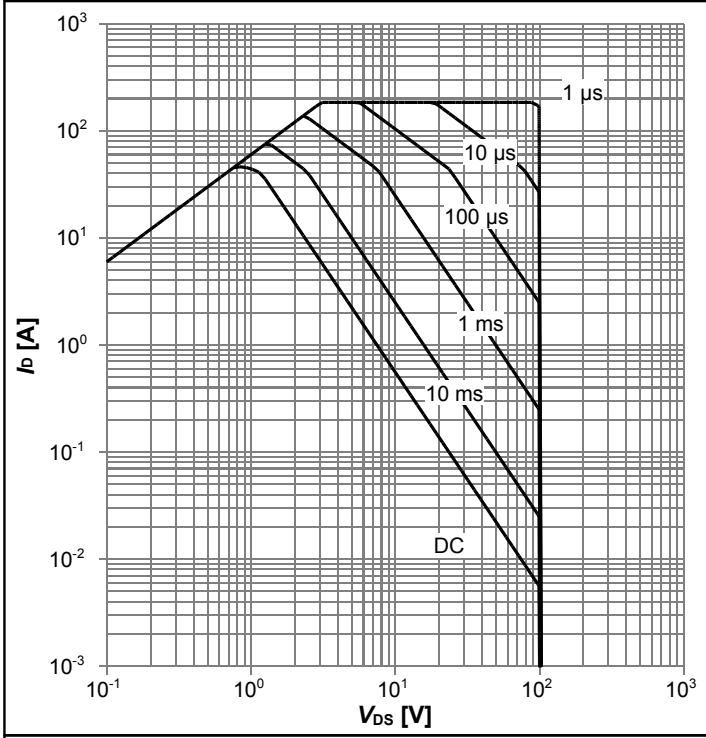
$P_{tot}=f(T_C)$

Diagram 2: Drain current



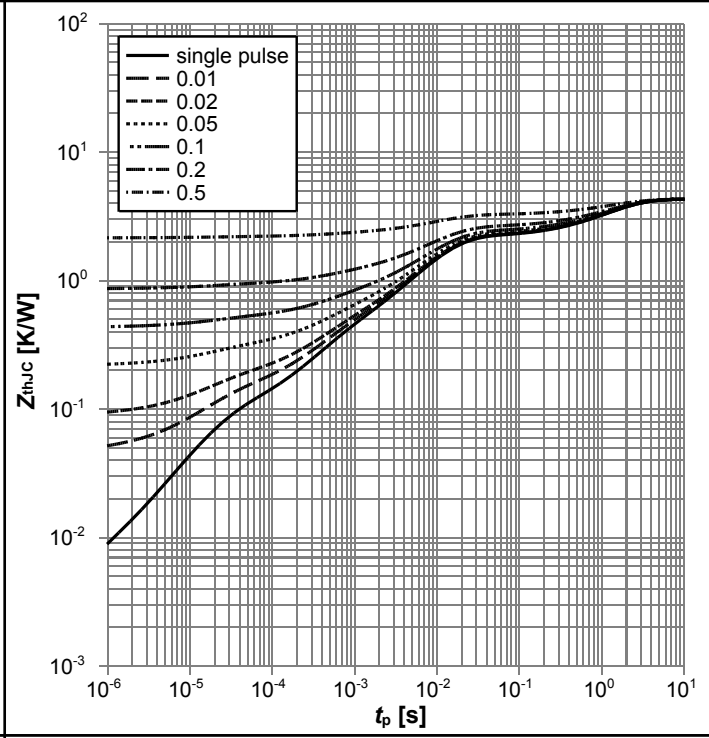
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



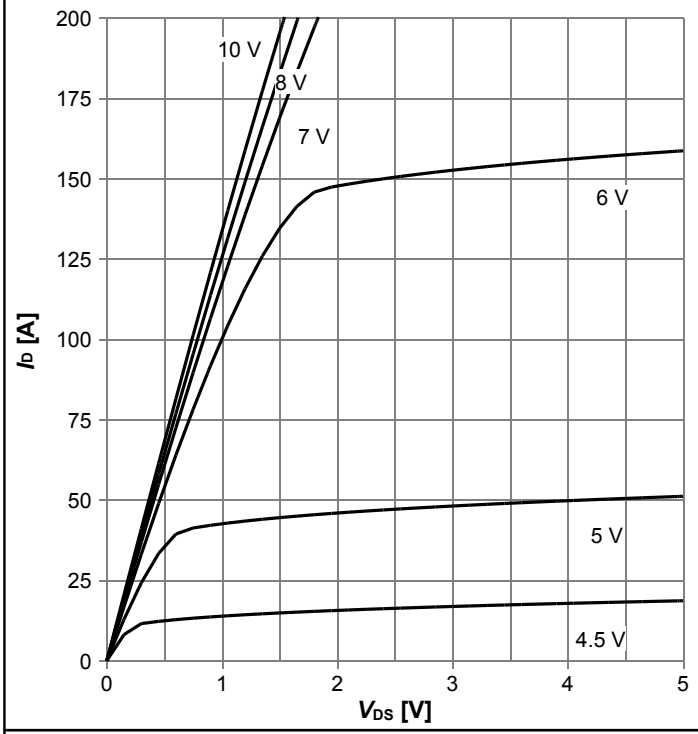
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Max. transient thermal impedance



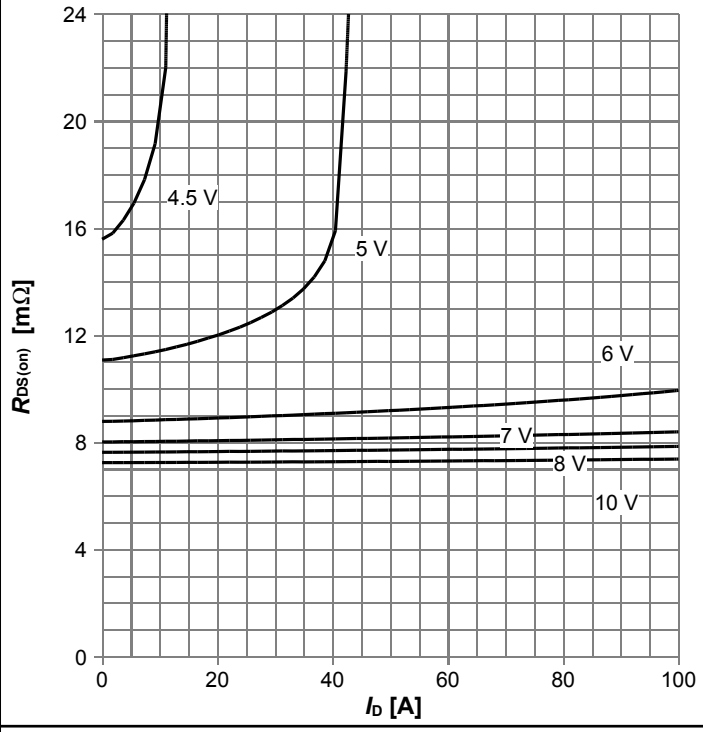
$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



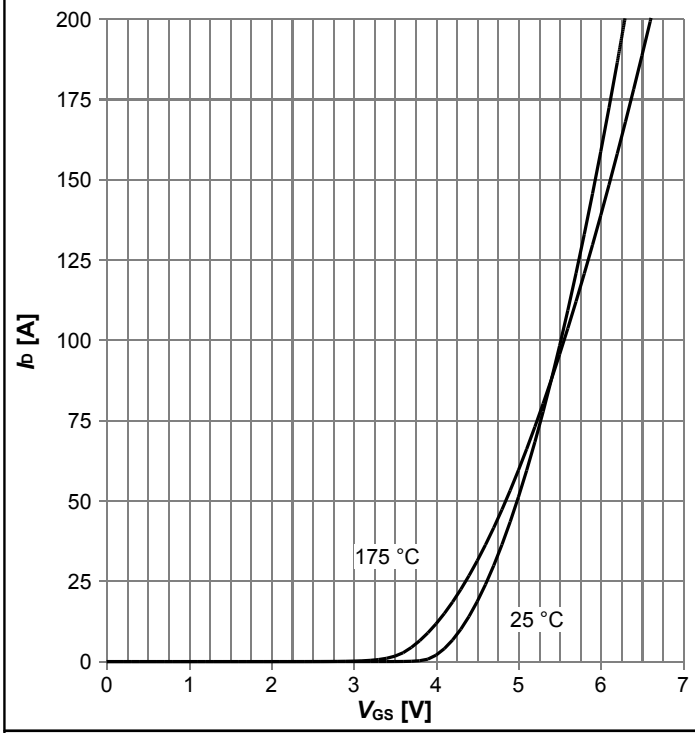
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



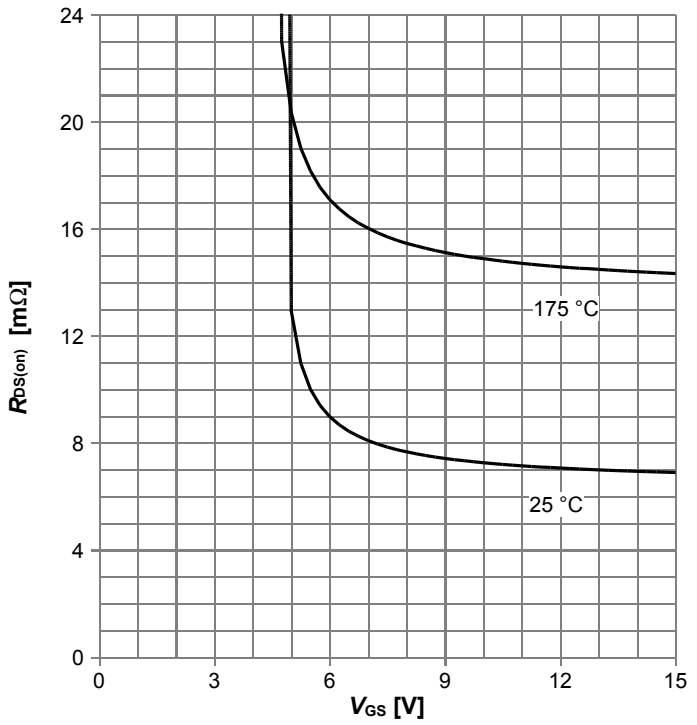
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



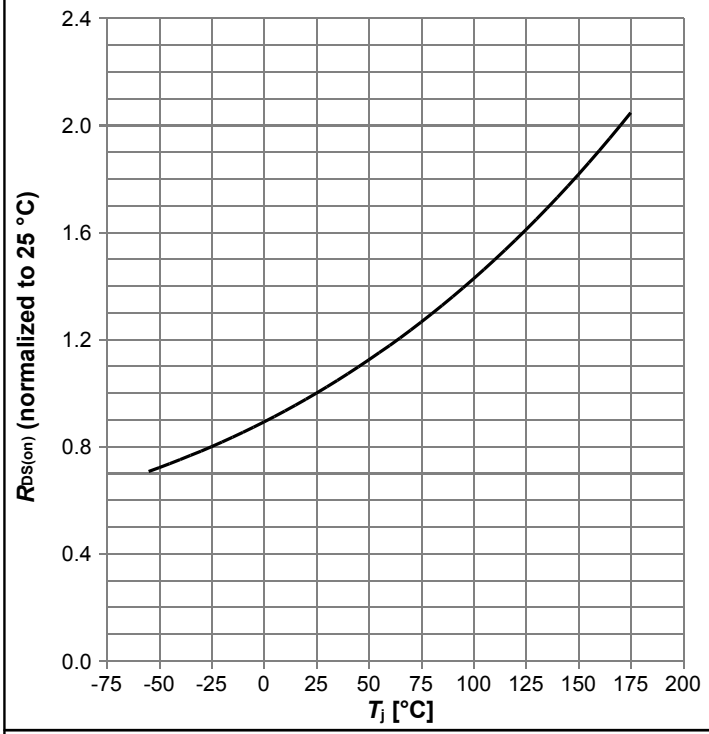
I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



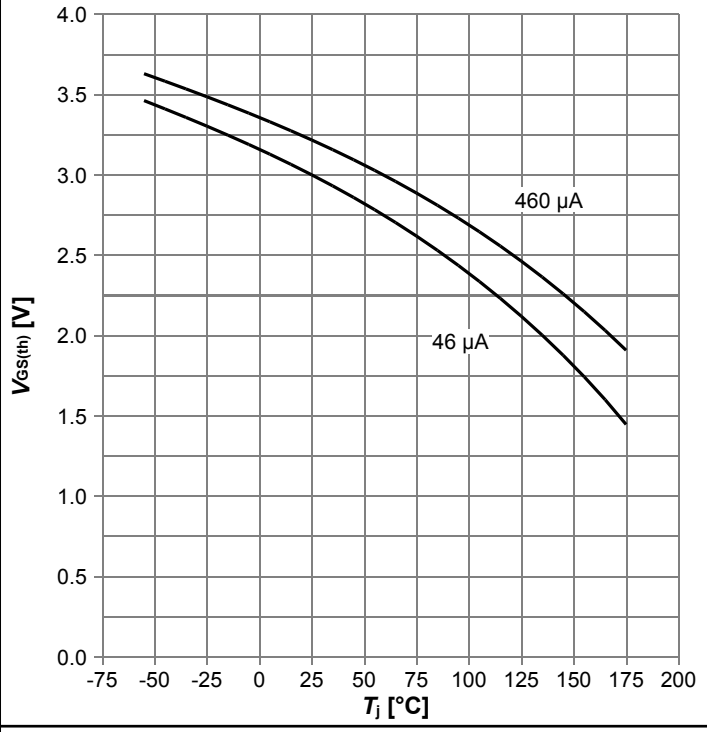
$R_{DS(on)}$=f(V_{GS}), I_D=30 A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



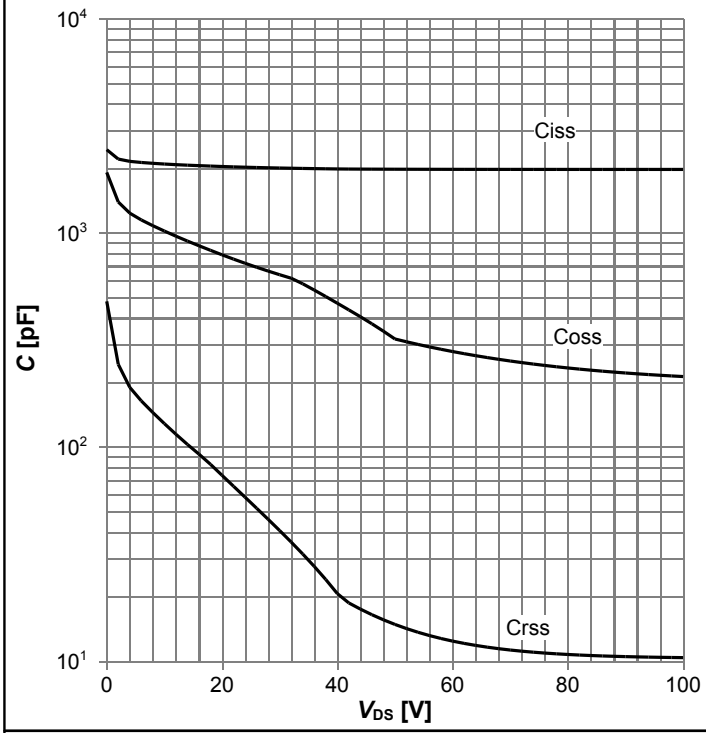
$R_{DS(on)}$=f(T_j), I_D=30 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



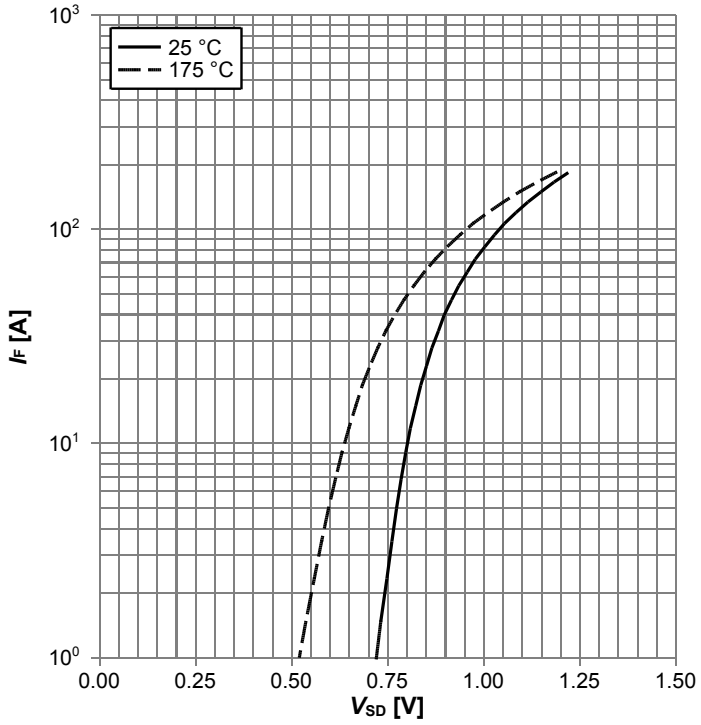
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



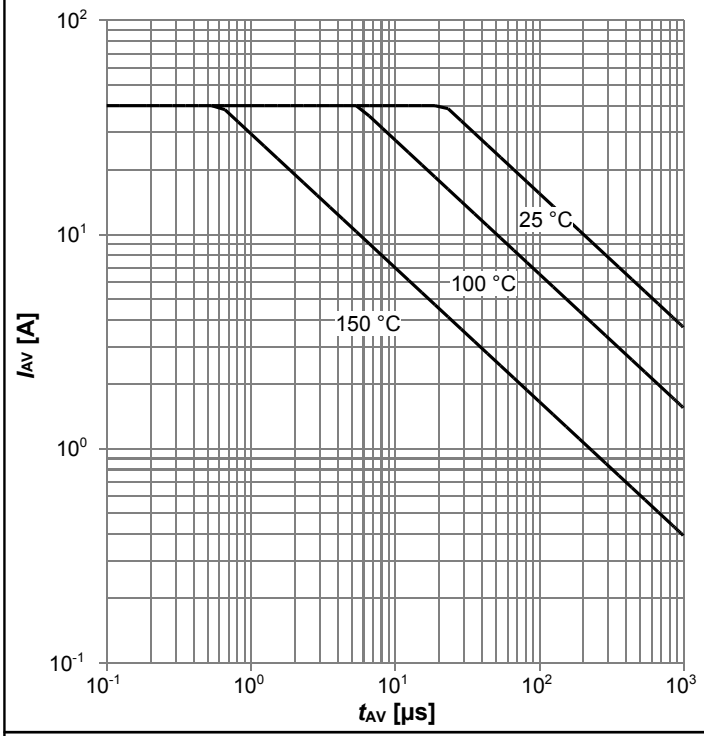
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Typ. forward characteristics of reverse diode



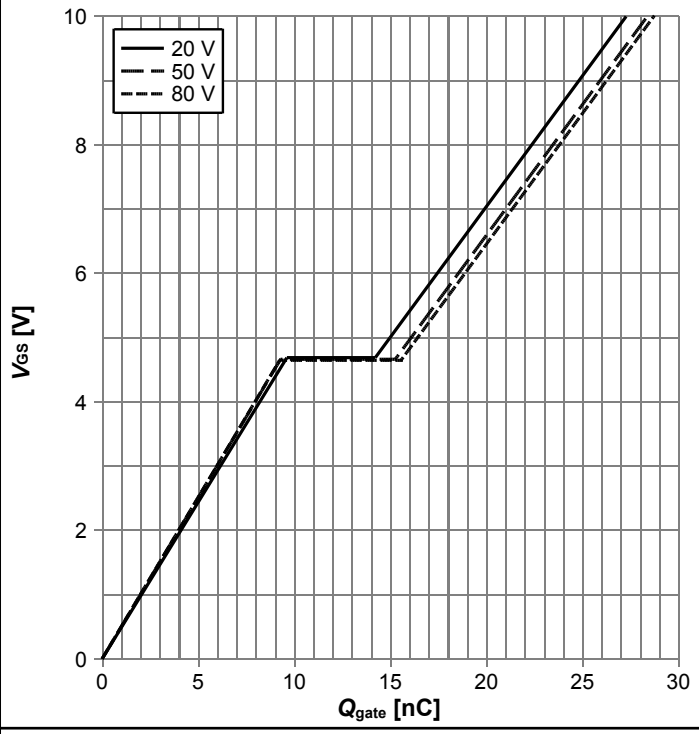
I_F=f(V_{SD}); parameter: T_j

Diagram 13: Avalanche characteristics



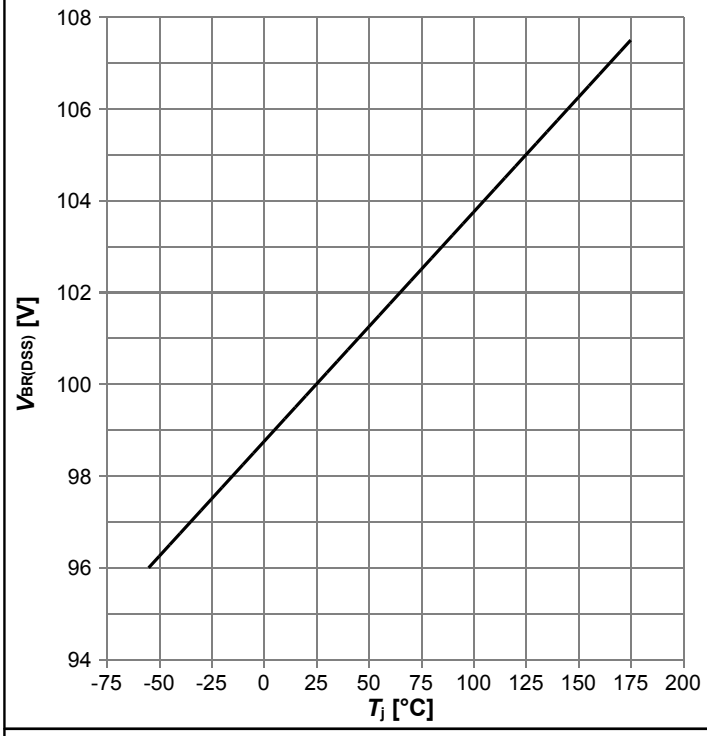
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



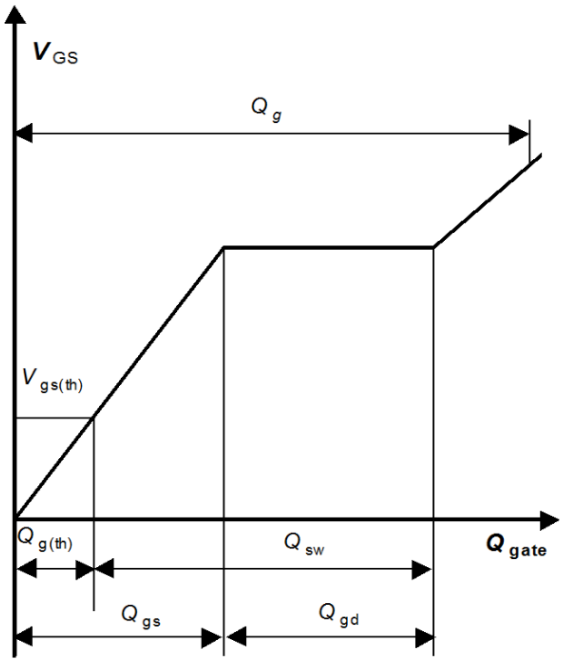
V_{GS}=f(Q_{gate}), I_D=30 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

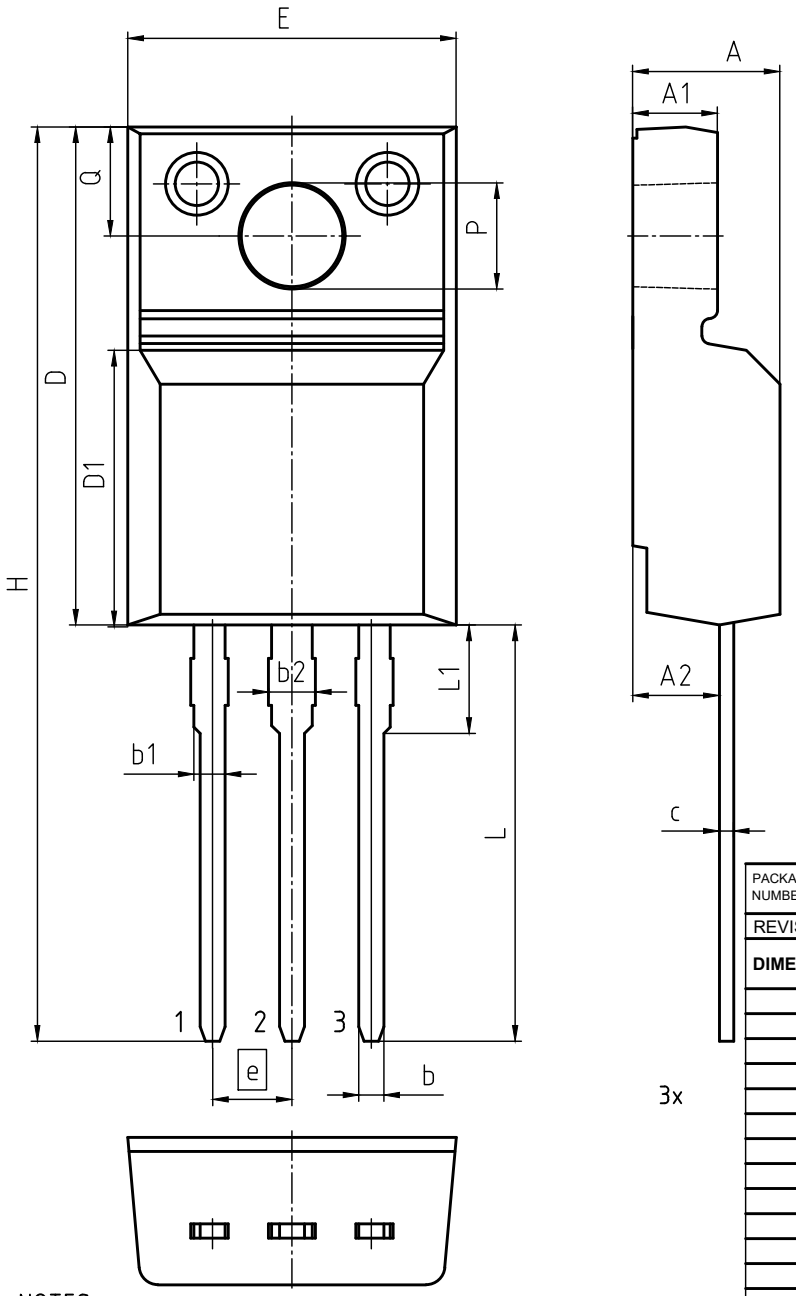


$V_{BR(DSS)}$=f(T_j); I_D=1 mA

Diagram Gate charge waveforms



5 Package Outlines



PACKAGE - GROUP NUMBER:	PG-TO220-3-U02	
REVISION: 01	DATE: 02.02.2021	
DIMENSIONS	**MILLIMETERS**	
	MIN.	MAX.
A	4.50	4.90
A1	2.34	2.85
A2	2.42	3.43
b	0.61	0.94
b1	0.76	1.45
b2	0.95	1.52
c	0.33	0.63
D	15.67	16.15
D1	8.66	9.83
E	9.63	10.75
e	2.54	
H	29.00	29.85
L	12.78	13.75
L1	2.83	3.67
øP	3.05	3.45
Q	3.20	3.50

NOTES:
DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS
GATE BURRS ARE LESS THAN 0.5 mm

Figure 1 Outline PG-TO220 FullPAK, dimensions in mm

Revision History

IPA082N10NF2S

Revision: 2022-06-14, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2021-03-16	Release of final version
2.1	2022-06-14	Skip condition "Operating and storage tempt.", update trr, Qrr and Diagram 12

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